

**AMENDMENTS TO THE CLAIMS**

**This listing of claims will replace all prior versions and listings of claims in the application:**

**LISTING OF CLAIMS:**

1. (currently amended): A curable resin composition,  
which contains an epoxy resin, ~~a solid polymer having a functional group to react with an epoxy group~~ a high molecular polymer having an epoxy group and a curing agent for an epoxy resin, no phase separation structure being observed in a matrix of a resin when a cured product is dyed with a heavy metal and observed with a transmission electron microscope,

wherein the high molecular polymer having an epoxy group has an epoxy equivalent of 200 to 1,000.

2. (original): The curable resin composition according to claim 1,  
wherein the cured product has a single  $\tan\delta$  peak in viscoelasticity spectrometry and the temperature of the peak is 120°C or higher.

3. (previously presented): The curable resin composition according to claim 1,  
wherein the cured product has a swelling ratio of 50% or less measured in a dimethyl sulfoxide solution heated at 120°C.

4. (previously presented): The curable resin composition according to claim 1,

wherein extracted water obtained by extracting an eluting component of the cured product with hot water at 110°C has pH not lower than 5.0 and lower than 8.5.

5. (previously presented): The curable resin composition according to claim 1, wherein extracted water obtained by extracting an eluting component of the cured product with hot water at 110°C has an electric conductivity of 100  $\mu$ S/cm or lower.

6. (previously presented): The curable resin composition according to claim 1, wherein the cured product has a dielectric constant of 3.5 or lower and a dielectric loss tangent of 0.02 or lower.

7. (currently amended): The curable resin composition according to claim 1, wherein the epoxy resin is an epoxy resin having a polycyclic hydrocarbon skeleton in the main chain and the solid polymer having the functional group to react with the epoxy group is a high-molecular polymer having an epoxy group and no inorganic filler is contained.

8. (original): The curable resin composition according to claim 7, wherein the epoxy resin having a polycyclic hydrocarbon skeleton in the main chain is an epoxy resin having a dicyclopentadiene skeleton or an epoxy resin having a naphthalene skeleton.

9. (currently amended): The curable resin composition according to claim 17,

wherein the high molecular polymer having an epoxy group has a weight-average molecular weight (Mw) of 10,000 or higher.

10. (cancelled).

11. (currently amended): The curable resin composition according to claim 17, wherein the high molecular polymer having an epoxy group is produced by suspension polymerization method.

12. (currently amended): The curable resin composition according to claim 1, which further contains a low elastic modulus substance having elastic modulus ( $G'$ ) in a range of  $1 \times 10^5$  to  $1 \times 10^8$  Pa at 20°C, ~~the low elastic modulus substance being dispersed like an island in non-compatible state with the epoxy resin and the solid polymer having the functional group to react with the epoxy group.~~

13. (withdrawn): A curable resin composition, which contains an epoxy resin composition obtainable by mixing an epoxy resin having a dicyclopentadiene skeleton, an epoxy resin having a naphthalene skeleton and a curing agent for an epoxy resin, and rubber particles having a core-shell structure, the core having a glass transition temperature of 20°C or lower and the shell having a glass transition temperature of 40°C or higher.

14. (currently amended): An adhesive epoxy resin paste,

which comprises the curable resin composition according to claim 1.

15. (original): An interlayer adhesive,  
which comprises the adhesive epoxy resin paste according to claim 14.

16. (original): A non-conductive paste,  
which comprises the adhesive epoxy resin paste according to claim 14.

17. (original): An underfill,  
which comprises the adhesive epoxy resin paste according to claim 14.

18. (currently amended): An adhesive epoxy resin sheet,  
which is ~~obtainable~~obtained by forming the curable resin composition according to claim  
1, in a sheet form.

19. (original): The adhesive epoxy resin sheet according to claim 18,  
wherein a heat-cured product obtained by heat curing at a temperature rising rate of  
45°C/min has a storage modulus ( $G'$ ) exceeding  $1 \times 10^3$  Pa.

20. (currently amended): The adhesive epoxy resin sheet according to claim 18,  
wherein the peak temperature of  $\tan\delta$  based on dynamic viscoelasticity is in a range of -  
20°C to 40°C before curing and 120°C or higher after curing.

21. (currently amended): A non-conductive film,  
which comprises the adhesive epoxy resin sheet according to claim 18.
22. (currently amended): A die attach film,  
which comprises the adhesive epoxy resin sheet according to claim 18.
23. (original): A conductive connection paste,  
wherein conductive fine particles are contained in the adhesive epoxy resin paste  
according to claim 14.
24. (original): An anisotropic conductive paste,  
which comprises the conductive connection paste according to claim 23.
25. (currently amended): A conductive connection sheet,  
which comprises the adhesive epoxy resin sheet according to claim 18, and conductive  
fine particles, at least a part of the conductive fine particles being exposed out of the adhesive  
epoxy resin sheet.
26. (currently amended): A conductive connection sheet,  
which is ~~obtainable~~ obtained by embedding conductive fine particles smaller than the  
thickness of the adhesive epoxy resin sheet in the adhesive epoxy resin sheet according to claim  
18.

27. (original): An anisotropic conductive film,

which comprises the conductive connection sheet according to claim 26.

28. (withdrawn): A conductive connection sheet,

which is formed by a pressure sensitive adhesive resin sheet comprising a pressure sensitive resin composition containing a resin provided with a pressure sensitive adhesive property by addition of a plasticizer and an epoxy resin having a naphthalene skeleton in liquid phase at normal temperature and conductive fine particles, the pressure sensitive adhesive resin sheet having a peak temperature of  $\tan\delta$  based on dynamic viscoelasticity in a range of  $-20^{\circ}\text{C}$  to  $40^{\circ}\text{C}$  before curing and  $120^{\circ}\text{C}$  or higher after curing and the conductive fine particles being arranged at any positions of the pressure sensitive adhesive resin sheet and at least a part of the conductive fine particles being exposed out of the pressure sensitive adhesive resin sheet.

29. (withdrawn): The conductive connection sheet according to claim 28,

wherein the pressure sensitive adhesive resin sheet after curing has an elongation percentage of 5% or lower after a pressure cooker test carried out under conditions of a temperature of  $120^{\circ}\text{C}$  and a humidity of 85% RH for 12 hours.

30. (previously presented): A flip chip tape,

which comprises a conductive connection sheet according to claim 25.

31. (currently amended): An electronic component joined body,

which is ~~obtainable~~obtained by joining a bump-shaped projected electrode of an electronic part to another electrode in electrically connected state by a curable resin composition according to claim 1. ~~the adhesive epoxy resin paste.~~

32. (currently amended): An electronic component joined body,  
which is ~~obtainable~~obtained by joining at least one kind circuit substrate selected from a group consisting of a metal lead frame, a ceramic substrate, a resin substrate, a silicon substrate, a compound semiconductor substrate, and a glass substrate by any of the curable resin composition according to claim 1.

33. (original): The electronic component joined body according to claim 32,  
wherein the resin substrate is a glass epoxy substrate, a bismaleimide triazine substrate or a polyimide substrate.